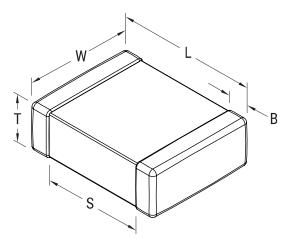


C0603X222K3GECTU

Aliases (C0603X222K3GEC7867) ESD SMD Comm C0G, Ceramic, 2,200 pF, 10%, 25 VDC, C0G, SMD, MLCC, Temperature Stable, Electro Static Discharge, Class I, 0603, 0.4 mm



Click here for the 3D model.

General Information	
Series	ESD SMD Comm COG
Style	SMD Chip
Description	SMD, MLCC, Temperature Stable, Electro Static Discharge, Class I
Features	Temperature Stable, Low ESR, Class I
RoHS	Yes
Termination	Flexible Termination
Marking	No
AEC-Q200	No
Typical Component Weight	4.6 mg
Shelf Life	78 Weeks
MSL	1

Dimensions	
Chip Size	0603
L	1.6mm +/-0.17mm
W	0.8mm +/-0.15mm
т	0.8mm +/-0.15mm
S	0.4mm MIN
В	0.45mm +/-0.15mm

Packaging Specifications

Packaging Packaging Quantity T&R, 180mm, Paper Tape 4000

Specifications	
Capacitance	2,200 pF
Measurement Condition	1 kHz 1.0Vrms
Tolerance	10%
Voltage DC	25 VDC
ESD Level per AEC-Q200	12,000 V ESD Level
Dielectric Withstanding Voltage	62.5 VDC
Temperature Range	-55/+125°C
Temp. Coefficient	COG
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1kHz 1.0Vrms
Dissipation Factor	0.1% 1 kHz 1.0Vrms
Aging Rate	0% Loss/Decade Hour
Insulation Resistance	100 GOhms

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